

For immediate release

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NEXX Systems Nimbus Sputtering Tool In Production at National Semiconductor in Malaysia

Wilmington, MA – January 7, 2003 – NEXX Systems today announced the production implementation of a Nimbus 310 sputter deposition system at the National Semiconductor plant in Melaka, Malaysia. The Nimbus was selected by National Semiconductor as the lowest cost-of-ownership tool on the market for deposition of under bump metallurgy (UBM) used in their flip chip process. The Nimbus was installed and operational in under two weeks, enabling National Semiconductor to bring online their latest technology for advanced flip chip and wafer level CSP products.

"We selected the Nimbus 310 sputtering tool from NEXX Systems for its superior performance due to the high throughput, fast wafer size change, and ease of use and maintenance," explained Sri Ganesh, senior process engineer, responsible for Wafer Bumping process at National Semiconductor in Malaysia.

National Semiconductor combines leading-edge analog and digital technologies to create highly integrated solutions for the information age. From complete systems on a single chip to high-performance multi-chip products and basic building blocks, National Semiconductor provides optimized solutions for the information appliance, personal computing, consumer and communications markets.

"Selection of the Nimbus 310 by National Semiconductor -- an acknowledged leader in advanced packaging solutions -- further solidifies NEXX Systems' goal of becoming the leading process equipment company for flip chip and advanced packaging technology," stated Richard Post, CEO of NEXX Systems.

NEXX Systems' products provide established platforms specifically focused on flip chip advanced packaging. Additional information can be found at: www.nexxsystems.com.

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